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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6100
Total RAM Bits	94208
Number of I/O	97
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec6e-4tn144i

Introduction

The LatticeECP/EC family of FPGA devices is optimized to deliver mainstream FPGA features at low cost. For maximum performance and value, the LatticeECP™ (EConomy Plus) FPGA concept combines an efficient FPGA fabric with high-speed dedicated functions. Lattice's first family to implement this approach is the LatticeECP-DSP™ (EConomy Plus DSP) family, providing dedicated high-performance DSP blocks on-chip. The LatticeEC™ (EConomy) family supports all the general purpose features of LatticeECP devices without dedicated function blocks to achieve lower cost solutions.

The LatticeECP/EC FPGA fabric, which was designed from the outset with low cost in mind, contains all the critical FPGA elements: LUT-based logic, distributed and embedded memory, PLLs and support for mainstream I/Os. Dedicated DDR memory interface logic is also included to support this memory that is becoming increasingly prevalent in cost-sensitive applications.

The ispLEVER® design tool suite from Lattice allows large complex designs to be efficiently implemented using the LatticeECP/EC FPGA family. Synthesis library support for LatticeECP/EC is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeECP/EC device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeECP/EC family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

Architecture Overview

The LatticeECP-DSP and LatticeEC architectures contain an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR), as shown in Figures 2-1 and 2-2. In addition, LatticeECP-DSP supports an additional row of DSP blocks, as shown in Figure 2-2.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional unit without RAM/ROM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM and register functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row. The PFU blocks are used on the outside rows. The rest of the core consists of rows of PFF blocks interspersed with rows of PFU blocks. For every three rows of PFF blocks there is a row of PFU blocks.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysI/O interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM or ROM.

The PFU, PFF, PIC and EBR Blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

At the end of the rows containing the sysMEM Blocks are the sysCLOCK Phase Locked Loop (PLL) Blocks. These PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeECP/EC architecture provides up to four PLLs per device.

Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG™ port which allows for serial or parallel device configuration. The LatticeECP/EC devices use 1.2V as their core voltage.

Figure 2-4. Slice Diagram

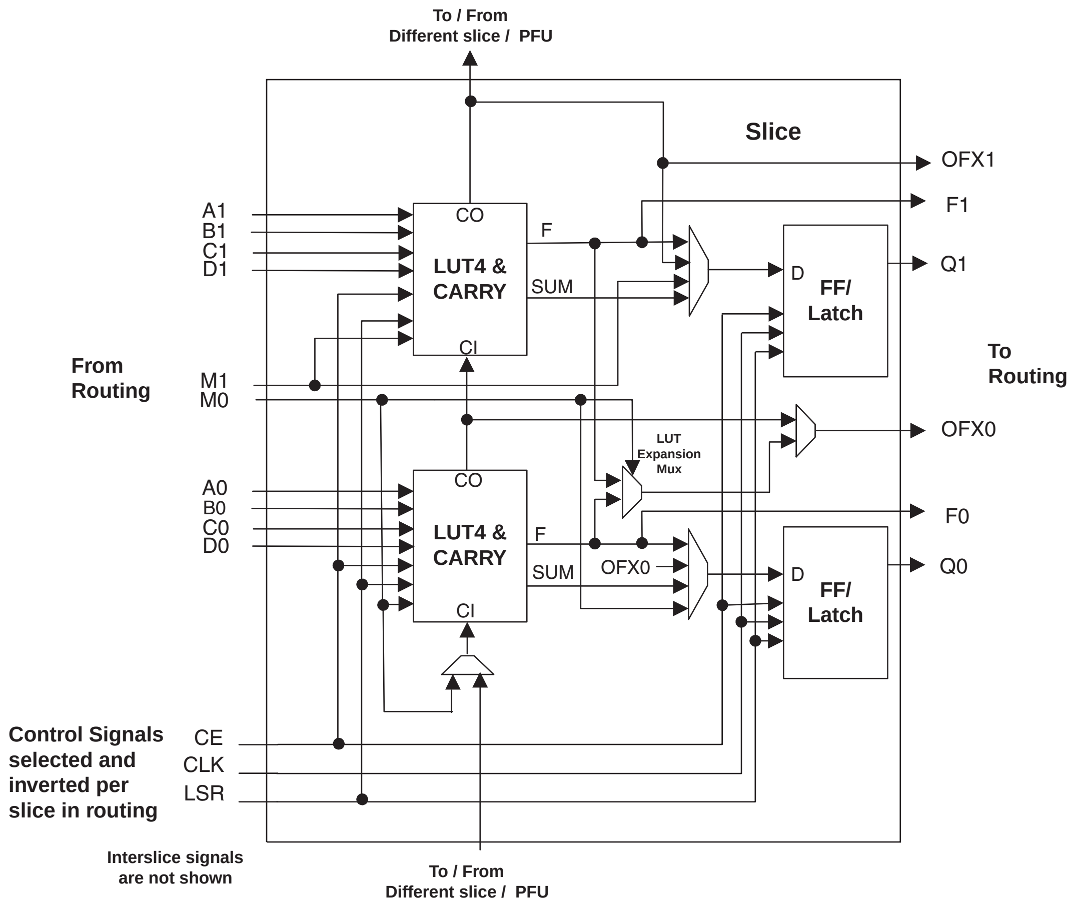


Table 2-1. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FCIN	Fast Carry In[1]
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register Outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8[2] MUX depending on the slice
Output	Inter-PFU signal	FCO	For the right most PFU the fast carry chain output[1]

1. See Figure 2-3 for connection details.
2. Requires two PFUs.

Polarity Control Logic

In a typical DDR Memory interface design, the phase relation between the incoming delayed DQS strobe and the internal system Clock (during the READ cycle) is unknown.

The LatticeECP/EC family contains dedicated circuits to transfer data between these domains. To prevent setup and hold violations at the domain transfer between DQS (delayed) and the system Clock a clock polarity selector is used. This changes the edge on which the data is registered in the synchronizing registers in the input register block. This requires evaluation at the start of each READ cycle for the correct clock polarity.

Prior to the READ operation in DDR memories DQS is in tristate (pulled by termination). The DDR memory device drives DQS low at the start of the preamble state. A dedicated circuit detects this transition. This signal is used to control the polarity of the clock to the synchronizing registers.

sysI/O Buffer

Each I/O is associated with a flexible buffer referred to as a sysI/O buffer. These buffers are arranged around the periphery of the device in eight groups referred to as Banks. The sysI/O buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL.

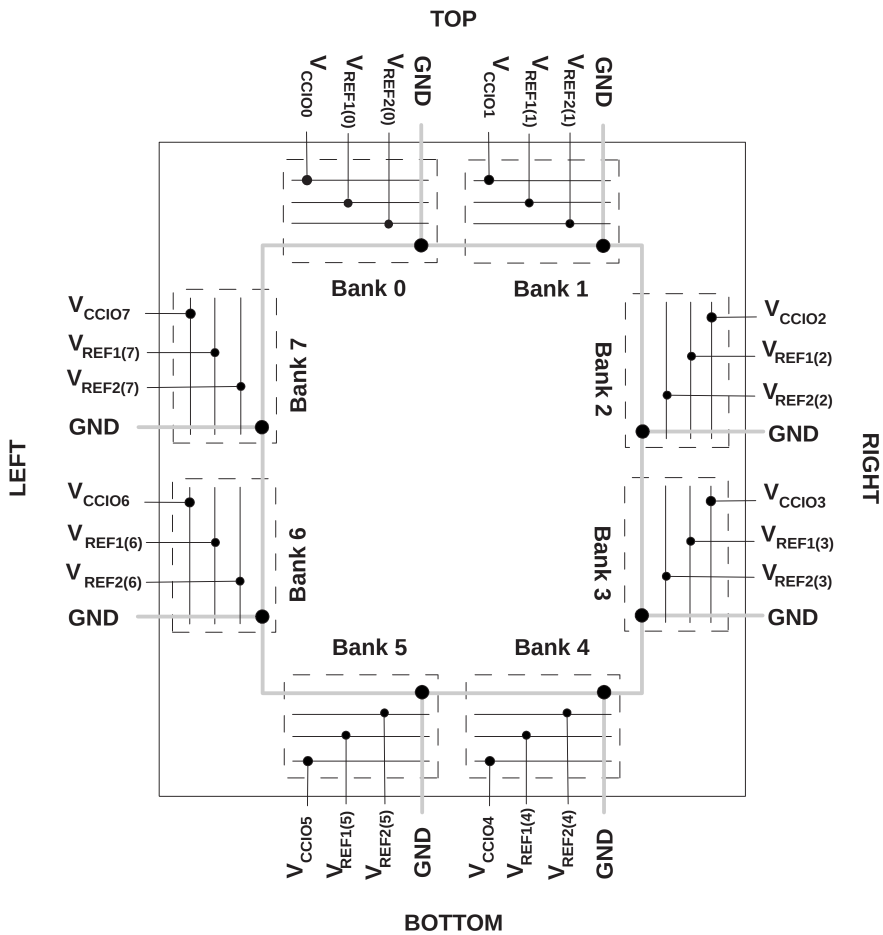
sysI/O Buffer Banks

LatticeECP/EC devices have eight sysI/O buffer banks; each is capable of supporting multiple I/O standards. Each sysI/O bank has its own I/O supply voltage (V_{CCIO}), and two voltage references V_{REF1} and V_{REF2} resources allowing each bank to be completely independent from each other. Figure 2-34 shows the eight banks and their associated supplies.

In the LatticeECP/EC devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS, PCI and PCI-X) are powered using $V_{CCIO.}$ LVTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as fixed threshold input independent of $V_{CCIO.}$ In addition to the bank V_{CCIO} supplies, the LatticeECP/EC devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that power all differential and referenced buffers.

Each bank can support up to two separate VREF voltages, VREF1 and VREF2 that set the threshold for the referenced input buffers. In the LatticeECP/EC devices, some dedicated I/O pins in a bank can be configured to be a reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

Figure 2-34. LatticeECP/EC Banks



LatticeECP/EC devices contain two types of sysI/O buffer pairs.

1. **Top and Bottom sysI/O Buffer Pairs (Single-Ended Outputs Only)**
   The sysI/O buffer pairs in the top and bottom banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

   The two pads in the pair are described as "true" and "comp", where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

   Only the I/Os on the top and bottom banks have programmable PCI clamps. These I/O banks also support hot socketing with IDK less than 1mA. Note that the PCI clamp is enabled after V_{CC}, V_{CCAUX} and V_{CCIO} are at valid operating levels and the device has been configured.

2. **Left and Right sysI/O Buffer Pairs (Differential and Single-Ended Outputs)**
   The sysI/O buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. The referenced input buffer can also be configured as a differential input. In these banks the two pads in the pair are described as "true" and "comp", where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

   Only the left and right banks have LVDS differential output drivers. See the I_{DK} specification for I/O leakage current during power-up.

Table 2-14. Supported Output Standards

Output Standard	Drive	V_{CCIO} (Nom.)
Single-ended Interfaces		
LVTTL	4mA, 8mA, 12mA, 16mA, 20mA	3.3
LVCMOS33	4mA, 8mA, 12mA 16mA, 20mA	3.3
LVCMOS25	4mA, 8mA, 12mA, 16mA, 20mA	2.5
LVCMOS18	4mA, 8mA, 12mA, 16mA	1.8
LVCMOS15	4mA, 8mA	1.5
LVCMOS12	2mA, 6mA	1.2
LVCMOS33, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS25, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS18, Open Drain	4mA, 8mA, 12mA 16mA	—
LVCMOS15, Open Drain	4mA, 8mA	—
LVCMOS12, Open Drain	2mA, 6mA	—
PCI33	N/A	3.3
HSTL18 Class I, II, III	N/A	1.8
HSTL15 Class I, III	N/A	1.5
SSTL3 Class I, II	N/A	3.3
SSTL2 Class I, II	N/A	2.5
SSTL18 Class I	N/A	1.8
Differential Interfaces		
Differential SSTL3, Class I, II	N/A	3.3
Differential SSTL2, Class I, II	N/A	2.5
Differential SSTL18, Class I	N/A	1.8
Differential HSTL18, Class I, II, III	N/A	1.8
Differential HSTL15, Class I, III	N/A	1.5
LVDS	N/A	2.5
BLVDS[1]	N/A	2.5
LVPECL[1]	N/A	3.3
RSDS[1]	N/A	2.5

1. Emulated with external resistors.

Hot Socketing

The LatticeECP/EC devices have been carefully designed to ensure predictable behavior during power-up and power-down. Power supplies can be sequenced in any order. During power up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled within specified limits, this allows for easy integration with the rest of the system. These capabilities make the LatticeECP/EC ideal for many multiple power supply and hot-swap applications.

Configuration and Testing

The following section describes the configuration and testing features of the LatticeECP/EC devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeECP/EC devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to

LatticeECP/EC Family Data Sheet DC and Switching Characteristics

September 2012 **Data Sheet**

Absolute Maximum Ratings[1, 2, 3]

Supply Voltage V_{CC} . . . . -0.5 to 1.32V

Supply Voltage V_{CCAUX} . . . . -0.5 to 3.75V

Supply Voltage V_{CCJ} . . . . -0.5 to 3.75V

Output Supply Voltage V_{CCIO} . . . . -0.5 to 3.75V

Dedicated Input Voltage Applied[4] . . . . -0.5 to 4.25V

I/O Tristate Voltage Applied [4]. . . . . -0.5 to 3.75V

Storage Temperature (Ambient) . . . . -65 to 150°C

Junction Temp. (Tj) . . . . +125°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage	1.14	1.26	V
V_{CCAUX}[3]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCPLL}	PLL Supply Voltage for ECP/EC33	1.14	1.26	V
V_{CCIO}[1, 2]	I/O Driver Supply Voltage	1.140	3.465	V
V_{CCJ}[1]	Supply Voltage for IEEE 1149.1 Test Access Port	1.140	3.465	V
t_{JCOM}	Junction Commercial Operation	0	85	°C
t_{JIND}	Junction Industrial Operation	-40	100	°C

1. If V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC}. If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as V_{CCAUX}.
2. See recommended voltages by I/O standard in subsequent table.
3. V_{CCAUX} ramp rate must not exceed 3mV/µs for commercial and 0.6 mV/µs for industrial device operations during power up when transitioning between 0.8V and 1.8V.

Hot Socketing Specifications[1, 2, 3, 4]

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Top and Bottom General Purpose sysI/Os (Banks 0, 1, 4 and 5), JTAG and Dedicated sysCONFIG Pins						
I_{DK_TB}	Input or I/O Leakage Current	0 ð V_{IN} ð V_{IH} (MAX.)	—	—	+/-1000	µA
Left and Right General Purpose sysI/Os (Banks 2, 3, 6 and 7)						
I_{DK_LR}	Input or I/O Leakage Current	V_{IN} ð V_{CCIO}	—	—	+/-1000	µA
		$V_{IN} > V_{CCIO}$	—	35	—	mA

1. Insensitive to sequence of V_{CC}, V_{CCAUX} and V_{CCIO}. However, assumes monotonic rise/fall rates for V_{CC}, V_{CCAUX} and V_{CCIO}.
2. 0 ð V_{CC} ð V_{CC} (MAX), 0 ð V_{CCIO} ð V_{CCIO} (MAX) or 0 ð V_{CCAUX} ð V_{CCAUX} (MAX).
3. I_{DK} is additive to I_{PU}, I_{PW} or I_{BH}.
4. LVCMOS and LVTTL only.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1]	Input or I/O Leakage	0 ð V_{IN} ð (V_{CCIO} - 0.2V)	—	—	10	µA
I_{IH}[1, 3]	Input or I/O High Leakage	(V_{CCIO} - 0.2V) ð V_{IH} ð 3.6V	—	—	40	µA
I_{PU}	I/O Active Pull-up Current	0 ð V_{IN} ð 0.7 V_{CCIO}	-30	—	-150	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) ð V_{IN} ð V_{IH} (MAX)	30	—	150	µA
I_{BHLS}	Bus Hold Low sustaining current	V_{IN} = V_{IL} (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High sustaining current	V_{IN} = 0.7V_{CCIO}	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive current	0 ð V_{IN} ð V_{IH} (MAX)	—	—	150	µA
I_{BHLH}	Bus Hold High Overdrive current	0 ð V_{IN} ð V_{IH} (MAX)	—	—	-150	µA
V_{BHT}	Bus Hold trip Points	0 ð V_{IN} ð V_{IH} (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C2	Dedicated Input Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25°C, f = 1.0MHz
3. For top and bottom general purpose I/O pins, when V_{IH} is higher than V_{CCIO}, a transient current typically of 30ns in duration or less with a peak current of 6mA can occur on the high-to-low transition. For left and right I/O banks, V_{IH} must be less than or equal to V_{CCIO}.

LatticeECP/EC External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Primary Clock without PLL)[1]									
t_{CO}[7]	Clock to Output - PIO Output Register	LFEC1	—	5.09	—	6.11	—	7.13	ns
		LFEC3	—	5.71	—	6.85	—	7.99	ns
		LFEC6	—	5.60	—	6.72	—	7.84	ns
		LFEC10	—	5.47	—	6.57	—	7.66	ns
		LFEC15	—	5.67	—	6.81	—	7.94	ns
		LFEC20	—	5.89	—	7.07	—	8.25	ns
		LFEC33	—	6.19	—	7.42	—	8.66	ns
t_{SU}[7]	Clock to Data Setup - PIO Input Register	LFEC1	-0.08	—	-0.10	—	-0.12	—	ns
		LFEC3	-0.70	—	-0.84	—	-0.98	—	ns
		LFEC6	-0.63	—	-0.76	—	-0.89	—	ns
		LFEC10	-0.43	—	-0.52	—	-0.61	—	ns
		LFEC15	-0.70	—	-0.84	—	-0.98	—	ns
		LFEC20	-0.88	—	-1.06	—	-1.24	—	ns
		LFEC33	-1.12	—	-1.34	—	-1.56	—	ns
t_H[7]	Clock to Data Hold - PIO Input Register	LFEC1	2.19	—	2.62	—	3.06	—	ns
		LFEC3	2.80	—	3.36	—	3.92	—	ns
		LFEC6	2.69	—	3.23	—	3.77	—	ns
		LFEC10	2.56	—	3.08	—	3.59	—	ns
		LFEC15	2.76	—	3.32	—	3.87	—	ns
		LFEC20	2.99	—	3.58	—	4.18	—	ns
		LFEC33	3.28	—	3.93	—	4.59	—	ns
t_{SU_DEL}[7]	Clock to Data Setup - PIO Input Register with Data Input Delay	LFEC1	3.36	—	4.03	—	4.70	—	ns
		LFEC3	2.74	—	3.29	—	3.84	—	ns
		LFEC6	2.81	—	3.37	—	3.93	—	ns
		LFEC10	3.01	—	3.61	—	4.21	—	ns
		LFEC15	2.74	—	3.29	—	3.83	—	ns
		LFEC20	2.56	—	3.07	—	3.58	—	ns
		LFEC33	2.32	—	2.79	—	3.25	—	ns
tH_DEL[7]	Clock to Data Hold - PIO Input Register with Input Data Delay	LFEC1	-1.31	—	-1.57	—	-1.83	—	ns
		LFEC3	-0.70	—	-0.83	—	-0.97	—	ns
		LFEC6	-0.80	—	-0.96	—	-1.12	—	ns
		LFEC10	-0.93	—	-1.12	—	-1.30	—	ns
		LFEC15	-0.73	—	-0.88	—	-1.02	—	ns
		LFEC20	-0.51	—	-0.61	—	-0.71	—	ns
		LFEC33	-0.22	—	-0.26	—	-0.30	—	ns
f_{MAX_IO}[2]	Clock Frequency of I/O and PFU Register	All	—	420	—	378	—	340	Mhz
DDR I/O Pin Parameters[3, 4, 5]									
t_{DVADQ}	Data Valid After DQS (DDR Read)	All	—	0.19	—	0.19	—	0.19	UI
t_{DVEDQ}	Data Hold After DQS (DDR Read)	All	0.67	—	0.67	—	0.67	—	UI

LatticeECP/EC Internal Switching Characteristics (Continued)

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.18	—	0.21	—	0.25	—	ns
t_{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.14	—	-0.17	—	-0.20	—	ns
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.47	—	1.76	—	2.05	ns
PLL Parameters								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns
DSP Block Timing[2, 3]								
t_{SUI_DSP}	Input Register Setup Time	-0.38	—	-0.30	—	-0.23	—	ns
t_{HI_DSP}	Input Register Hold Time	0.71	—	0.86	—	1.00	—	ns
t_{SUP_DSP}	Pipeline Register Setup Time	3.31	—	3.98	—	4.64	—	ns
t_{HP_DSP}	Pipeline Register Hold Time	0.71	—	0.86	—	1.00	—	ns
t_{SUO_DSP}[4]	Output Register Setup Time	5.54	—	6.64	—	7.75	—	ns
t_{HO_DSP}[4]	Output Register Hold Time	0.71	—	0.86	—	1.00	—	ns
t_{COI_DSP}[4]	Input Register Clock to Output Time	—	7.50	—	9.00	—	10.50	ns
t_{COP_DSP}[4]	Pipeline Register Clock to Output Time	—	4.66	—	5.60	—	6.53	ns
t_{COO_DSP}	Output Register Clock to Output Time	—	1.47	—	1.77	—	2.06	ns
$t_{SUADSUB}$	AdSub Input Register Setup Time	-0.38	—	-0.30	—	-0.23	—	ns
t_{HADSUB}	AdSub Input Register Hold Time	0.71	—	0.86	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.
2. These parameters apply to LatticeECP devices only.
3. DSP Block is configured in Multiply Add/Sub 18 x 18 Mode.
4. These parameters include the Adder Subtractor block in the path.

Timing v.G 0.30

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		25	—	420	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	—	420	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	—	210	MHz
f_{VCO}	PLL VCO Frequency		420	—	840	MHz
f_{PFD}	Phase Detector Input Frequency		25	—	—	MHz
AC Characteristics						
t_{DT}	Output Clock Duty Cycle	Default Duty Cycle Elected[3]	45	50	55	%
t_{PH}[4]	Output Phase Accuracy		—	—	0.05	UI
t_{OPJIT}[1]	Output Clock Period Jitter	f_{OUT} >= 100MHz	—	—	+/- 125	ps
		f_{OUT} < 100MHz	—	—	0.02	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	—	+/- 200	ps
t_W	Output Clock Pulse Width	At 90% or 10%[3]	1	—	—	ns
t_{LOCK}[2]	PLL Lock-in Time		—	—	150	µs
t_{PA}	Programmable Delay Unit		100	250	450	ps
t_{IPJIT}	Input Clock Period Jitter		—	—	+/- 200	ps
t_{FBKDLY}	External Feedback Delay		—	—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	—	ns
t_{RST}	RST Pulse Width		10	—	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with clean reference clock.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Using LVDS output buffers.
4. Relative to CLKOP.

Timing v.G 0.30

Pin Information Summary

Pin Type		LFEC1			LFEC3				LFECP6/EC6				LFECP/EC10		
		100-TQFP	144-TQFP	208-PQFP	100-TQFP	144-TQFP	208-PQFP	256-fpBGA	144-TQFP	208-PQFP	256-fpBGA	484-fpBGA	208-PQFP	256-fpBGA	484-fpBGA
Single Ended User I/O		67	97	112	67	97	145	160	97	147	195	224	147	195	288
Differential Pair User I/O		29	46	56	29	46	72	80	46	72	97	112	72	97	144
Configu-ration	Dedicated	13	13	13	13	13	13	13	13	13	13	13	13	13	13
	Muxed	48	48	48	48	48	48	48	48	48	48	48	56	56	56
TAP		5	5	5	5	5	5	5	5	5	5	5	5	5	5
Dedicated (total without supplies)		80	110	160	80	110	160	208	110	160	208	373	160	208	373
V_{CC}		2	3	3	2	3	3	10	4	4	10	20	6	10	20
V_{CCAUX}		2	2	2	4	4	4	4	2	4	2	12	4	2	12
V_{CCPLL}		0	0	0	0	0	0	0	0	0	0	0	0	0	0
V_{CCIO}	Bank0	1	2	2	1	2	3	2	2	3	2	4	3	2	4
	Bank1	1	2	2	1	2	2	2	2	2	2	4	2	2	4
	Bank2	1	1	1	2	2	2	2	1	2	2	4	2	2	4
	Bank3	1	2	2	1	2	2	2	2	2	2	4	2	2	4
	Bank4	1	2	2	1	2	2	2	2	2	2	4	2	2	4
	Bank5	1	2	2	1	2	2	2	2	3	2	4	3	2	4
	Bank6	1	2	2	1	2	2	2	2	2	2	4	2	2	4
	Bank7	1	1	1	2	2	2	2	1	2	2	4	2	2	4
GND, GND0-GND7		8	13	13	8	13	16	20	14	18	20	44	20	20	44
NC		0	2	51	0	2	9	35	0	4	0	139	0	0	75
Single Ended/ Differen-tial I/O Pair per Bank	Bank 0	11/5	14/7	16/8	11/5	14/7	26/13	32/16	14/7	26/13	32/16	32/16	26/13	32/16	48/24
	Bank 1	11/5	13/6	16/8	11/5	13/6	16/8	16/8	13/6	17/8	18/9	32/16	17/8	18/9	32/16
	Bank 2	3/1	8/4	8/4	3/1	8/4	14/7	16/8	8/4	14/7	16/8	16/8	14/7	16/8	32/16
	Bank 3	8/4	13/6	16/8	8/4	13/6	16/8	16/8	13/6	16/8	32/16	32/16	16/8	32/16	32/16
	Bank 4	12/4	14/6	16/8	12/4	14/6	16/8	16/8	14/6	17/8	17/8	32/16	17/8	17/8	32/16
	Bank 5	9/4	13/6	16/8	9/4	13/6	26/13	32/16	13/6	26/13	32/16	32/16	26/13	32/16	48/24
	Bank 6	5/2	14/7	16/8	5/2	14/7	16/8	16/8	14/7	16/8	32/16	32/16	16/8	32/16	32/16
	Bank 7	8/4	8/4	8/4	8/4	8/4	15/7	16/8	8/4	15/7	16/8	16/8	15/7	16/8	32/16
V_{CCJ}		1	1	1	1	1	1	1	1	1	1	1	1	1	1

Note: During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.

LFECP/EC6, LFECP/EC10 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFECP6/LFEC6				LFECP10/LFEC10			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
169	PT21A	1	T		PT29A	1	T	
170	PT20B	1	C		PT28B	1	C	
171	PT20A	1	T		PT28A	1	T	
172	PT19B	1	C	VREF2_1	PT27B	1	C	VREF2_1
173	PT19A	1	T	VREF1_1	PT27A	1	T	VREF1_1
174	PT18B	1	C		PT26B	1	C	
175	PT18A	1	T		PT26A	1	T	
176	VCCIO1	1			VCCIO1	1		
177	VCCAUX	-			VCCAUX	-		
178	PT17B	0	C	PCLKC0_0	PT25B	0	C	PCLKC0_0
179	GND0	0			GND0	0		
180	PT17A	0	T	PCLKT0_0	PT25A	0	T	PCLKT0_0
181	PT16B	0	C	VREF1_0	PT24B	0	C	VREF1_0
182	PT16A	0	T	VREF2_0	PT24A	0	T	VREF2_0
183	PT15B	0	C		PT23B	0	C	
184	PT15A	0	T		PT23A	0	T	
185	PT14B	0	C		PT22B	0	C	
186	PT14A	0	T	TDQS14	PT22A	0	T	TDQS22
187	VCCIO0	0			VCCIO0	0		
188	PT13B	0	C		PT21B	0	C	
189	GND0	0			GND0	0		
190	PT13A	0	T		PT21A	0	T	
191	PT12B	0	C		PT20B	0	C	
192	PT12A	0	T		PT20A	0	T	
193	PT11B	0	C		PT19B	0	C	
194	PT11A	0	T		PT19A	0	T	
195	PT10B	0	C		PT18B	0	C	
196	PT10A	0	T		PT18A	0	T	
197	VCCIO0	0			VCCIO0	0		
198	PT6B	0	C		PT6B	0	C	
199	PT6A	0	T	TDQS6	PT6A	0	T	TDQS6
200	PT5B	0	C		PT5B	0	C	
201	PT5A	0	T		PT5A	0	T	
202	PT4B	0	C		PT4B	0	C	
203	PT4A	0	T		PT4A	0	T	
204	PT3B	0	C		PT3B	0	C	
205	PT3A	0	T		PT3A	0	T	
206	PT2B	0	C		PT2B	0	C	
207	PT2A	0	T		PT2A	0	T	
208	VCCIO0	0			VCCIO0	0		

*Double bonded to the pin.

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
GND	GND7	7			GND7	7		
D4	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7
D3	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7
C3	PL3A	7	T		PL3A	7	T	
C2	PL3B	7	C		PL3B	7	C	
B1	PL4A	7	T		PL4A	7	T	
C1	PL4B	7	C		PL4B	7	C	
E3	PL5A	7	T		PL5A	7	T	
E4	PL5B	7	C		PL5B	7	C	
F4	PL6A	7	T	LDQS6	PL6A	7	T	LDQS6
F5	PL6B	7	C		PL6B	7	C	
G4	PL7A	7	T		PL7A	7	T	
G3	PL7B	7	C		PL7B	7	C	
D2	PL8A	7	T		PL8A	7	T	
D1	PL8B	7	C		PL8B	7	C	
E1	PL9A	7	T	PCLKT7_0	PL9A	7	T	PCLKT7_0
GND	GND7	7			GND7	7		
E2	PL9B	7	C	PCLKC7_0	PL9B	7	C	PCLKC7_0
F3	XRES	6			XRES	6		
G5	NC	-			PL11A	6	T	
H5	NC	-			PL11B	6	C	
F2	NC	-			PL12A	6	T	
F1	NC	-			PL12B	6	C	
H4	NC	-			PL13A	6	T	
H3	NC	-			PL13B	6	C	
G2	NC	-			PL14A	6	T	
-	-	-			GND6	6		
G1	NC	-			PL14B	6	C	
J4	NC	-			PL15A	6	T	LDQS15
J3	NC	-			PL15B	6	C	
J5	NC	-			PL16A	6	T	
K5	NC	-			PL16B	6	C	
H2	NC	-			PL17A	6	T	
H1	NC	-			PL17B	6	C	
J2	NC	-			PL18A	6	T	
-	-	-			GND6	6		
J1	NC	-			PL18B	6	C	
K4	TCK	6			TCK	6		
K3	TDI	6			TDI	6		
L3	TMS	6			TMS	6		
L5	TDO	6			TDO	6		
L4	VCCJ	6			VCCJ	6		

LFECP/EC10 and LFECP/EC15 Logic Signal Connections: 256 fpBGA

Ball Number	LFECP10/LFECP10 Ball Function	Bank	LVDS	Dual Function	LFECP15/LFEC15 Ball Function	Bank	LVDS	Dual Function
GND	GND7	7			GND7	7		
D4	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7
D3	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7
GND	GND7	7			GND7	7		
C3	PL12A	7	T		PL16A	7	T	
C2	PL12B	7	C		PL16B	7	C	
B1	PL13A	7	T		PL17A	7	T	
C1	PL13B	7	C		PL17B	7	C	
E3	PL14A	7	T		PL18A	7	T	
GND	GND7	7			GND7	7		
-	-	-			GND7	7		
E4	PL14B	7	C		PL18B	7	C	
F4	PL15A	7	T	LDQS15	PL19A	7	T	LDQS19
F5	PL15B	7	C		PL19B	7	C	
G4	PL16A	7	T		PL20A	7	T	
G3	PL16B	7	C		PL20B	7	C	
D2	PL17A	7	T		PL21A	7	T	
D1	PL17B	7	C		PL21B	7	C	
E1	PL18A	7	T	PCLKT7_0	PL22A	7	T	PCLKT7_0
GND	GND7	7			GND7	7		
E2	PL18B	7	C	PCLKC7_0	PL22B	7	C	PCLKC7_0
F3	XRES	6			XRES	6		
G5	PL20A	6	T		PL24A	6	T	
H5	PL20B	6	C		PL24B	6	C	
F2	PL21A	6	T		PL25A	6	T	
F1	PL21B	6	C		PL25B	6	C	
H4	PL22A	6	T		PL26A	6	T	
H3	PL22B	6	C		PL26B	6	C	
G2	PL23A	6	T		PL27A	6	T	
GND	GND6	6			GND6	6		
G1	PL23B	6	C		PL27B	6	C	
J4	PL24A	6	T	LDQS24	PL28A	6	T	LDQS28
J3	PL24B	6	C		PL28B	6	C	
J5	PL25A	6	T		PL29A	6	T	
K5	PL25B	6	C		PL29B	6	C	
H2	PL26A	6	T		PL30A	6	T	
H1	PL26B	6	C		PL30B	6	C	
J2	PL27A	6	T		PL31A	6	T	
GND	GND6	6			GND6	6		
J1	PL27B	6	C		PL31B	6	C	
K4	TCK	6			TCK	6		
K3	TDI	6			TDI	6		

LFECP/EC6, LFECP/EC10, LFECP/EC15 Logic Signal Connections: 484 fpBGA (Cont.)

LFECP6/LFEC6					LFECP10/LFEC10					LFECP/LFEC15				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
A4	NC	-			A4	PT9B	0	C		A4	PT9B	0	C	
B4	NC	-			B4	PT9A	0	T		B4	PT9A	0	T	
C4	NC	-			C4	PT8B	0	C		C4	PT8B	0	C	
C5	NC	-			C5	PT8A	0	T		C5	PT8A	0	T	
D6	NC	-			D6	PT7B	0	C		D6	PT7B	0	C	
B5	NC	-			B5	PT7A	0	T		B5	PT7A	0	T	
E6	NC	-			E6	PT6B	0	C		E6	PT6B	0	C	
C6	NC	-			C6	PT6A	0	T	TDQS6	C6	PT6A	0	T	TDQS6
A3	NC	-			A3	PT5B	0	C		A3	PT5B	0	C	
B3	NC	-			B3	PT5A	0	T		B3	PT5A	0	T	
F6	NC	-			F6	PT4B	0	C		F6	PT4B	0	C	
D5	NC	-			D5	PT4A	0	T		D5	PT4A	0	T	
F7	NC	-			F7	PT3B	0	C		F7	PT3B	0	C	
E8	NC	-			E8	PT3A	0	T		E8	PT3A	0	T	
G6	NC	-			G6	PT2B	0	C		G6	PT2B	0	C	
E7	NC	-			E7	PT2A	0	T		E7	PT2A	0	T	
GND	-	-			GND	GND0	0			GND	GND0	0		
A1	GND	-			A1	GND	-			A1	GND	-		
A22	GND	-			A22	GND	-			A22	GND	-		
AB1	GND	-			AB1	GND	-			AB1	GND	-		
AB22	GND	-			AB22	GND	-			AB22	GND	-		
H15	GND	-			H15	GND	-			H15	GND	-		
H8	GND	-			H8	GND	-			H8	GND	-		
J10	GND	-			J10	GND	-			J10	GND	-		
J11	GND	-			J11	GND	-			J11	GND	-		
J12	GND	-			J12	GND	-			J12	GND	-		
J13	GND	-			J13	GND	-			J13	GND	-		
J14	GND	-			J14	GND	-			J14	GND	-		
J9	GND	-			J9	GND	-			J9	GND	-		
K10	GND	-			K10	GND	-			K10	GND	-		
K11	GND	-			K11	GND	-			K11	GND	-		
K12	GND	-			K12	GND	-			K12	GND	-		
K13	GND	-			K13	GND	-			K13	GND	-		
K14	GND	-			K14	GND	-			K14	GND	-		
K9	GND	-			K9	GND	-			K9	GND	-		
L10	GND	-			L10	GND	-			L10	GND	-		
L11	GND	-			L11	GND	-			L11	GND	-		
L12	GND	-			L12	GND	-			L12	GND	-		
L13	GND	-			L13	GND	-			L13	GND	-		
L14	GND	-			L14	GND	-			L14	GND	-		
L9	GND	-			L9	GND	-			L9	GND	-		
M10	GND	-			M10	GND	-			M10	GND	-		
M11	GND	-			M11	GND	-			M11	GND	-		
M12	GND	-			M12	GND	-			M12	GND	-		
M13	GND	-			M13	GND	-			M13	GND	-		
M14	GND	-			M14	GND	-			M14	GND	-		
M9	GND	-			M9	GND	-			M9	GND	-		
N10	GND	-			N10	GND	-			N10	GND	-		
N11	GND	-			N11	GND	-			N11	GND	-		
N12	GND	-			N12	GND	-			N12	GND	-		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
GND	GND7	7			GND	GND7	7		
E3	PL2A	7	T	VREF2_7	E3	PL2A	7	T	VREF2_7
E4	PL2B	7	C	VREF1_7	E4	PL2B	7	C	VREF1_7
E5	NC	-			E5	PL6A	7	T	LDQS6
D5	NC	-			D5	PL6B	7	C	
F4	NC	-			F4	PL7A	7	T	
F5	NC	-			F5	PL7B	7	C	
C3	NC	-			C3	PL8A	7	T	
D3	NC	-			D3	PL8B	7	C	
C2	NC	-			C2	PL9A	7	T	
-	-	-			GND	GND7	7		
B2	NC	-			B2	PL9B	7	C	
B1	PL3A	7	T		B1	PL10A	7	T	
C1	PL3B	7	C		C1	PL10B	7	C	
F3	PL4A	7	T		F3	PL11A	7	T	
G3	PL4B	7	C		G3	PL11B	7	C	
D2	PL5A	7	T		D2	PL12A	7	T	
E2	PL5B	7	C		E2	PL12B	7	C	
-	-	-			GND	GND7	7		
D1	PL6A	7	T	LDQS6	D1	PL14A	7	T	LDQS14
E1	PL6B	7	C		E1	PL14B	7	C	
F2	PL7A	7	T		F2	PL15A	7	T	
G2	PL7B	7	C		G2	PL15B	7	C	
F6	PL8A	7	T	LUM0_PLLT_IN_A	F6	PL16A	7	T	LUM0_PLLT_IN_A
G6	PL8B	7	C	LUM0_PLLC_IN_A	G6	PL16B	7	C	LUM0_PLLC_IN_A
H4	PL9A	7	T	LUM0_PLLT_FB_A	H4	PL17A	7	T	LUM0_PLLT_FB_A
GND	GND7	7			GND	GND7	7		
G4	PL9B	7	C	LUM0_PLLC_FB_A	G4	PL17B	7	C	LUM0_PLLC_FB_A
H6	NC	-			H6	PL19A	7	T	
J7	NC	-			J7	PL19B	7	C	
G5	NC	-			G5	PL20A	7	T	
H5	NC	-			H5	PL20B	7	C	
H3	NC	-			H3	PL21A	7	T	
J3	NC	-			J3	PL21B	7	C	
H2	NC	-			H2	PL22A	7	T	
-	-	-			GND	GND7	7		
J2	NC	-			J2	PL22B	7	C	
J4	PL11A	7	T		J4	PL23A	7	T	LDQS23
J5	PL11B	7	C		J5	PL23B	7	C	
K4	PL12A	7	T		K4	PL24A	7	T	
K5	PL12B	7	C		K5	PL24B	7	C	
J6	PL13A	7	T		J6	PL25A	7	T	

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
D13	PT32B	0	C	VREF1_0	D13	PT32B	0	C	VREF1_0
C13	PT32A	0	T	VREF2_0	C13	PT32A	0	T	VREF2_0
A13	PT31B	0	C		A13	PT31B	0	C	
B13	PT31A	0	T		B13	PT31A	0	T	
F13	PT30B	0	C		F13	PT30B	0	C	
F12	PT30A	0	T	TDQS30	F12	PT30A	0	T	TDQS30
A12	PT29B	0	C		A12	PT29B	0	C	
GND	GND0	0			GND	GND0	0		
B12	PT29A	0	T		B12	PT29A	0	T	
A11	PT28B	0	C		A11	PT28B	0	C	
B11	PT28A	0	T		B11	PT28A	0	T	
D12	PT27B	0	C		D12	PT27B	0	C	
C12	PT27A	0	T		C12	PT27A	0	T	
B10	PT26B	0	C		B10	PT26B	0	C	
A10	PT26A	0	T		A10	PT26A	0	T	
G12	PT25B	0	C		G12	PT25B	0	C	
GND	GND0	0			GND	GND0	0		
A9	PT25A	0	T		A9	PT25A	0	T	
E12	PT24B	0	C		E12	PT24B	0	C	
B9	PT24A	0	T		B9	PT24A	0	T	
F11	PT23B	0	C		F11	PT23B	0	C	
A8	PT23A	0	T		A8	PT23A	0	T	
D11	PT22B	0	C		D11	PT22B	0	C	
C11	PT22A	0	T	TDQS22	C11	PT22A	0	T	TDQS22
B8	PT21B	0	C		B8	PT21B	0	C	
GND	GND0	0			GND	GND0	0		
B7	PT21A	0	T		B7	PT21A	0	T	
E11	PT20B	0	C		E11	PT20B	0	C	
A7	PT20A	0	T		A7	PT20A	0	T	
G11	PT19B	0	C		G11	PT19B	0	C	
C7	PT19A	0	T		C7	PT19A	0	T	
G10	PT18B	0	C		G10	PT18B	0	C	
C6	PT18A	0	T		C6	PT18A	0	T	
C10	PT17B	0	C		C10	PT17B	0	C	
GND	GND0	0			GND	GND0	0		
D10	PT17A	0	T		D10	PT17A	0	T	
F10	PT16B	0	C		F10	PT16B	0	C	
A6	PT16A	0	T		A6	PT16A	0	T	
E10	PT15B	0	C		E10	PT15B	0	C	
C9	PT15A	0	T		C9	PT15A	0	T	
G9	PT14B	0	C		G9	PT14B	0	C	
D9	PT14A	0	T	TDQS14	D9	PT14A	0	T	TDQS14

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
M10	GND	-			M10	GND	-		
M11	GND	-			M11	GND	-		
M12	GND	-			M12	GND	-		
M13	GND	-			M13	GND	-		
M14	GND	-			M14	GND	-		
M15	GND	-			M15	GND	-		
M16	GND	-			M16	GND	-		
M17	GND	-			M17	GND	-		
N10	GND	-			N10	GND	-		
N11	GND	-			N11	GND	-		
N12	GND	-			N12	GND	-		
N13	GND	-			N13	GND	-		
N14	GND	-			N14	GND	-		
N15	GND	-			N15	GND	-		
N16	GND	-			N16	GND	-		
N17	GND	-			N17	GND	-		
P10	GND	-			P10	GND	-		
P11	GND	-			P11	GND	-		
P12	GND	-			P12	GND	-		
P13	GND	-			P13	GND	-		
P14	GND	-			P14	GND	-		
P15	GND	-			P15	GND	-		
P16	GND	-			P16	GND	-		
P17	GND	-			P17	GND	-		
R10	GND	-			R10	GND	-		
R11	GND	-			R11	GND	-		
R12	GND	-			R12	GND	-		
R13	GND	-			R13	GND	-		
R14	GND	-			R14	GND	-		
R15	GND	-			R15	GND	-		
R16	GND	-			R16	GND	-		
R17	GND	-			R17	GND	-		
T10	GND	-			T10	GND	-		
T11	GND	-			T11	GND	-		
T12	GND	-			T12	GND	-		
T13	GND	-			T13	GND	-		
T14	GND	-			T14	GND	-		
T15	GND	-			T15	GND	-		
T16	GND	-			T16	GND	-		
T17	GND	-			T17	GND	-		
U10	GND	-			U10	GND	-		
U11	GND	-			U11	GND	-		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
H7	VCCAUX	-			H7	VCCAUX	-		
J19	VCCAUX	-			J19	VCCAUX	-		
J8	VCCAUX	-			J8	VCCAUX	-		
K7	VCCAUX	-			K7	VCCAUX	-		
L20	VCCAUX	-			L20	VCCAUX	-		
M20	VCCAUX	-			M20	VCCAUX	-		
M7	VCCAUX	-			M7	VCCAUX	-		
N20	VCCAUX	-			N20	VCCAUX	-		
P20	VCCAUX	-			P20	VCCAUX	-		
P7	VCCAUX	-			P7	VCCAUX	-		
T20	VCCAUX	-			T20	VCCAUX	-		
T7	VCCAUX	-			T7	VCCAUX	-		
T8	VCCAUX	-			T8	VCCAUX	-		
V19	VCCAUX	-			V19	VCCAUX	-		
V7	VCCAUX	-			V7	VCCAUX	-		
W20	VCCAUX	-			W20	VCCAUX	-		
Y13	VCCAUX	-			Y13	VCCAUX	-		
Y7	VCCAUX	-			Y7	VCCAUX	-		
K19	VCC[1]	-			K19	VCCPLL	-		
L8	VCC[1]	-			L8	VCCPLL	-		
U19	VCC[1]	-			U19	VCCPLL	-		
U8	VCC[1]	-			U8	VCCPLL	-		

1. Tied to V_{CCPLL}.